
Architectural Challenges for mm-scale Sensor Nodes

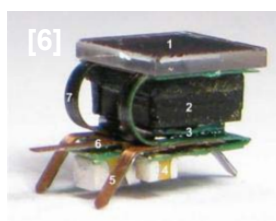
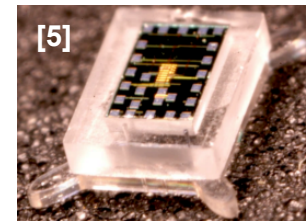
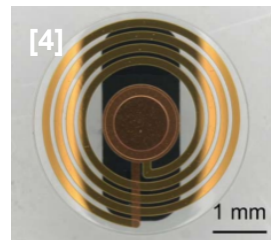
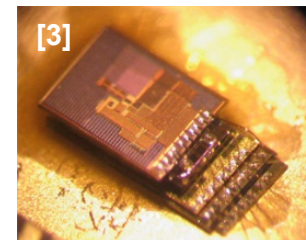
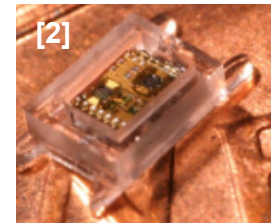
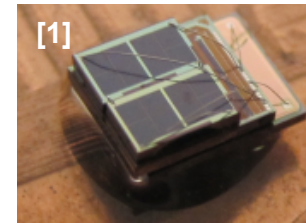
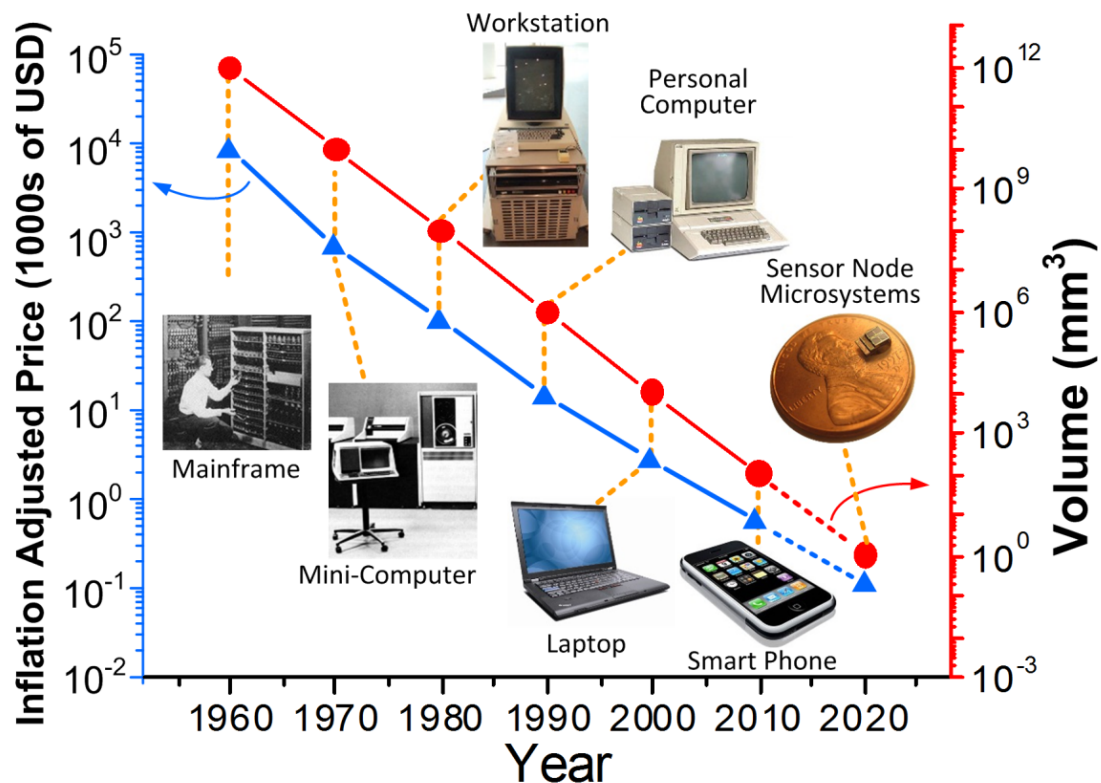
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mm-Scale Sensor Nodes



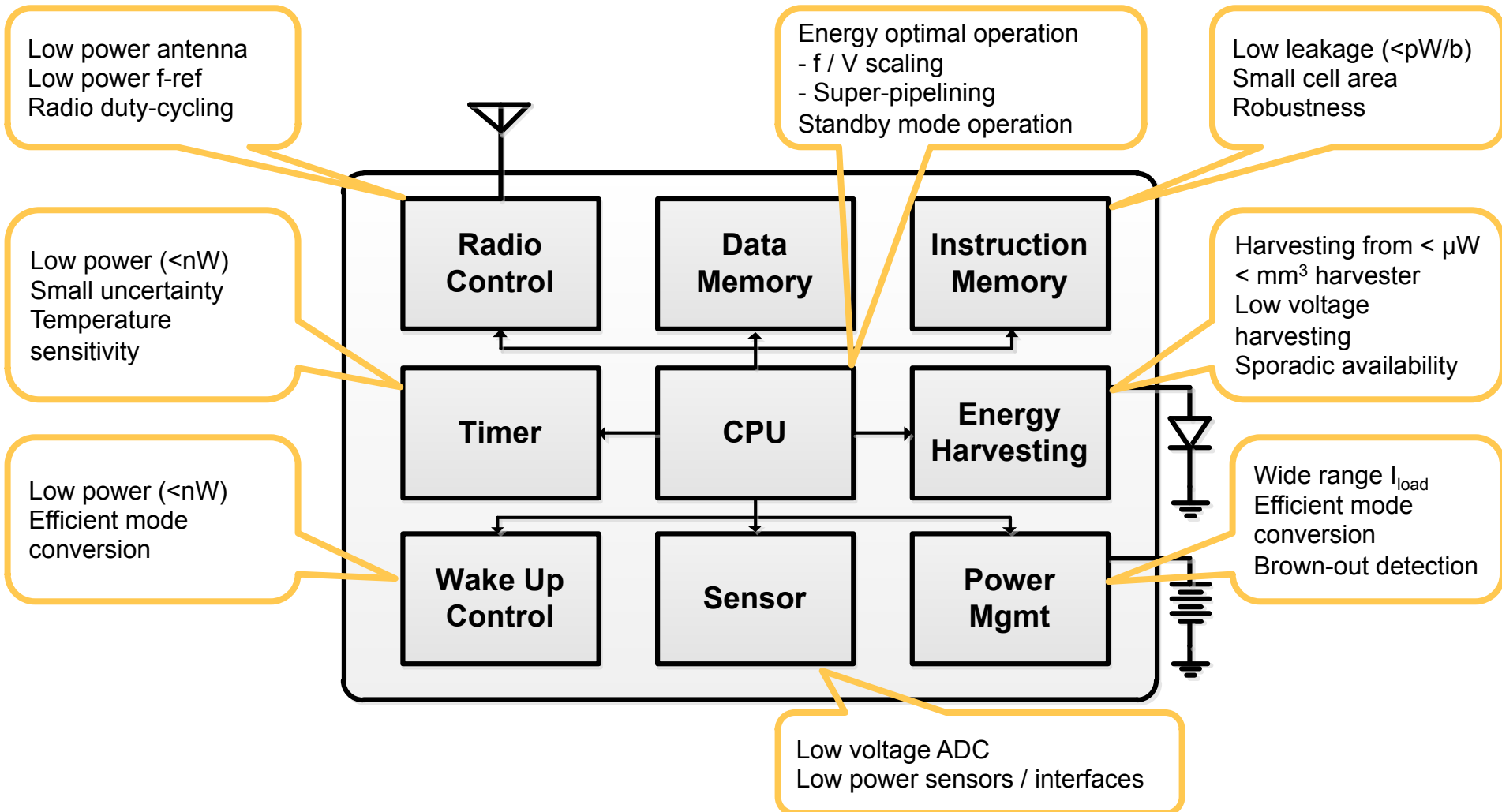
Emergence of mm-scale systems

- Smaller form-factor
- Cheaper price

- [1] G. Chen et al. ISSCC 2010
- [2] G. Chen et al. ISSCC 2011
- [3] Y. Lee et al. ISSCC 2012
- [4] P-J. Chen et al. JMEMS 2010
- [5] R. Haque et al. MEMS 2011
- [6] R. Casanova ISSCC 2009

mm-Scale Sensor Nodes

■ Key enabler: Low power circuit technologies

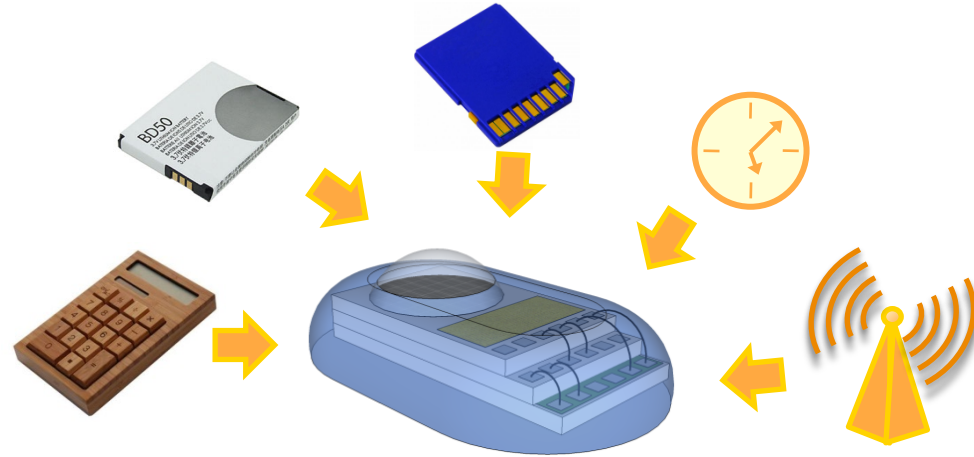


Challenges in mm-Scale Sensors

- Building a “SYSTEM” out of low power building blocks

- Integration requirements

- Volume limit
- Energy limit
- Controllability



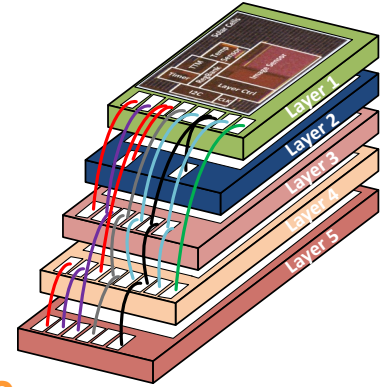
- Extremely wide application space

- Medical / Environmental
Structural Integrity / Surveillance
Building Management / and so on ...



Layer Based Modular Architecture

- Layer approach
 - Maximizing Si area in limited volume
 - Modularization
 - Technology optimization



Generic Layers

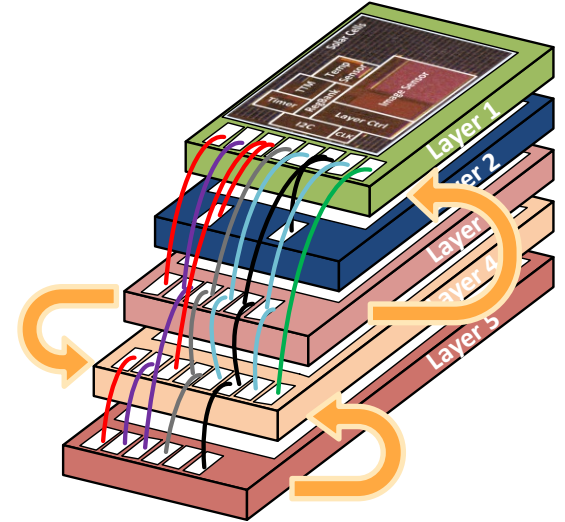
| |
|----------------------------|
| Processor |
| Flash Memory |
| Decap |
| Battery |
| Power Mng. E-Harvesting |

Application-specific Layers

| | |
|---------------------------|-------------------------|
| Imager | Motion Detection |
| Pressure Sensing (C to D) | Temperature Sensing |
| ECG monitor | Strain Sensing (R to D) |
| Light Sensing | Analog Voltage (ADC) |
| Near Field Radio | Far Field Radio |

Inter-Layer Interconnect

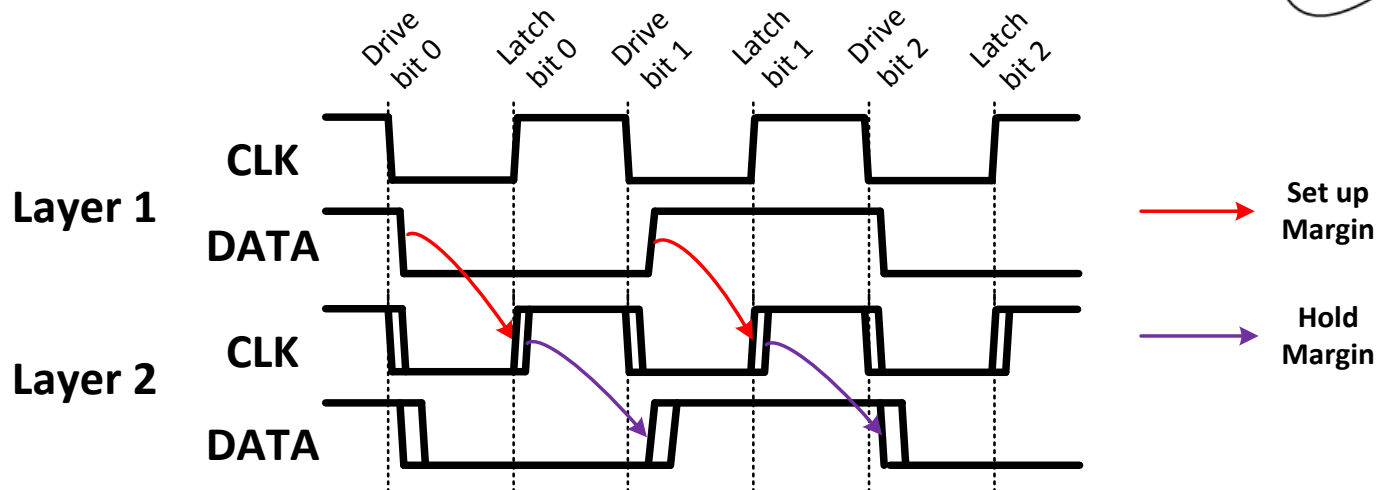
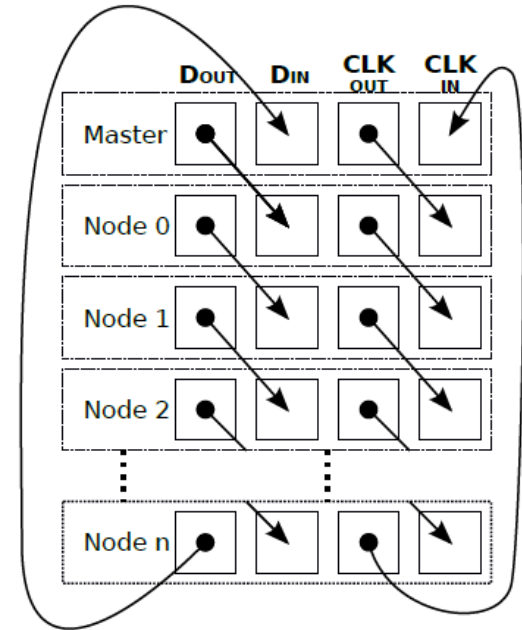
- How are the layers connected?
 - Delivery of Power
 - Control
 - Data exchange
- Traditional solutions
 - I²C
 - Bidirectional – pull up resistor power
 - Distributed clock control – clock generation on each device
 - SPI
 - >3 wires - limited expansion
 - No slave TX initiation / slave ACK
 - No slave to slave
- Need low power solution for control & data exchange



MBus: Low Power Inter-Layer Interconnect

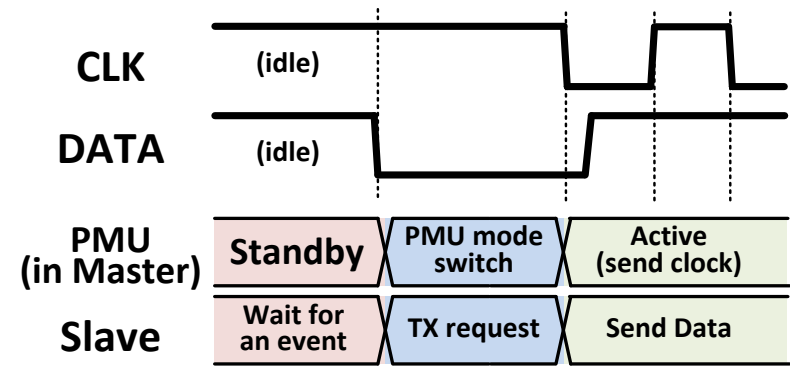
■ MBus

- 1 Master, multiple Slave layers
- 2 wires: CLK, DATA
- Unidirectional: Daisy-chained
- 2 phase clocking: Improve setup/hold tolerance
 - for arbitrary layer combination
 - for irregular loading

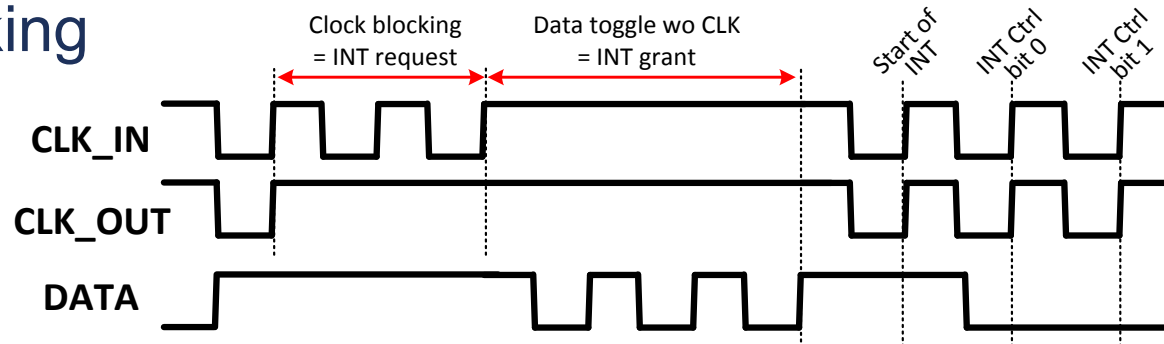


MBus: Low Power Inter-Layer Interconnect

- CLK driven by Master layer
 - ➔ No clock generation on other layers
 - ➔ Slave request TX by DATA pull down
 - ➔ Request wake up by DATA pull down



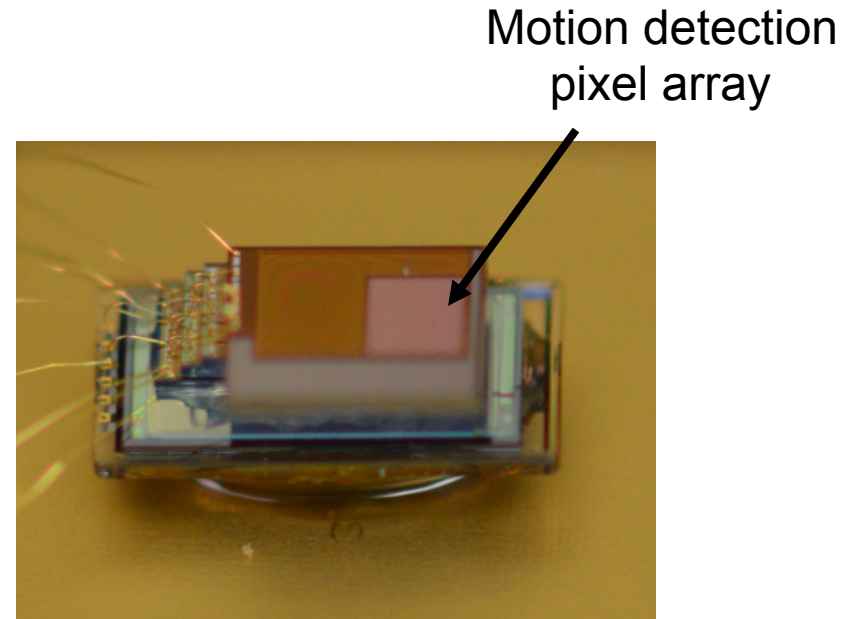
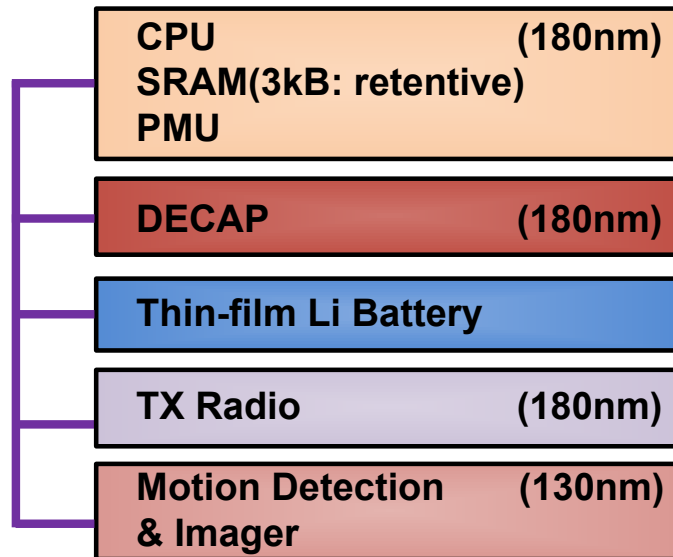
- Interrupt by clock blocking
 - ➔ Prioritize messages
 - ➔ Reset bus



- Termination sequence
 - ➔ Utilize interrupt as termination sequence
 - ➔ Enable slave ACK (control bit) & arbitrary length message

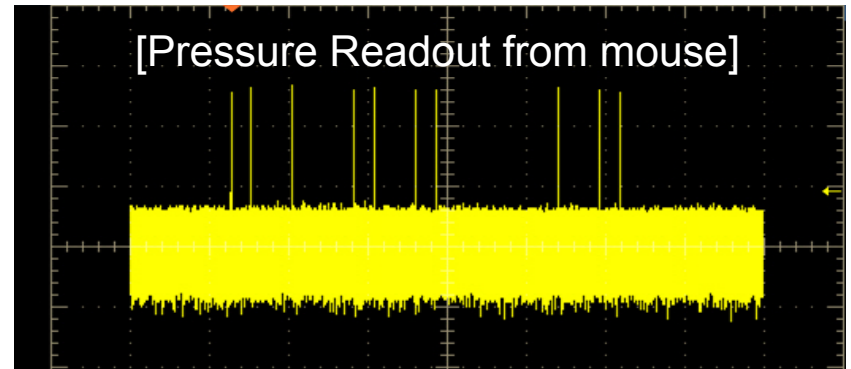
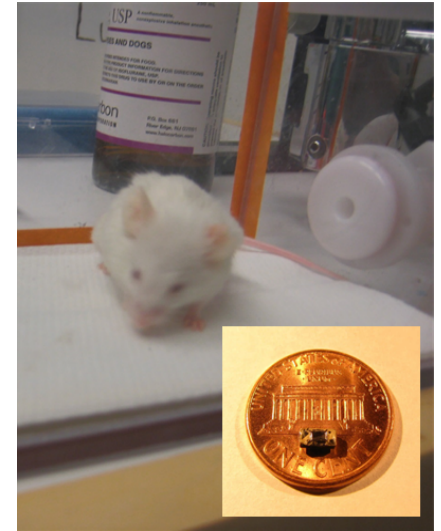
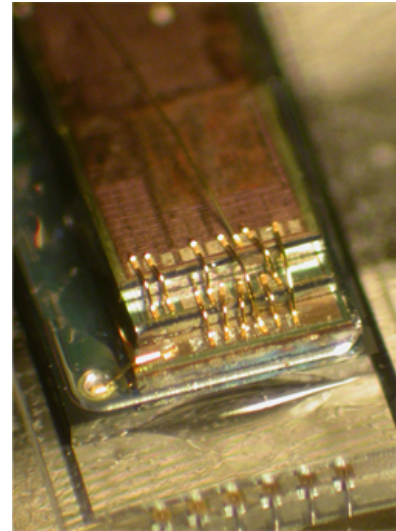
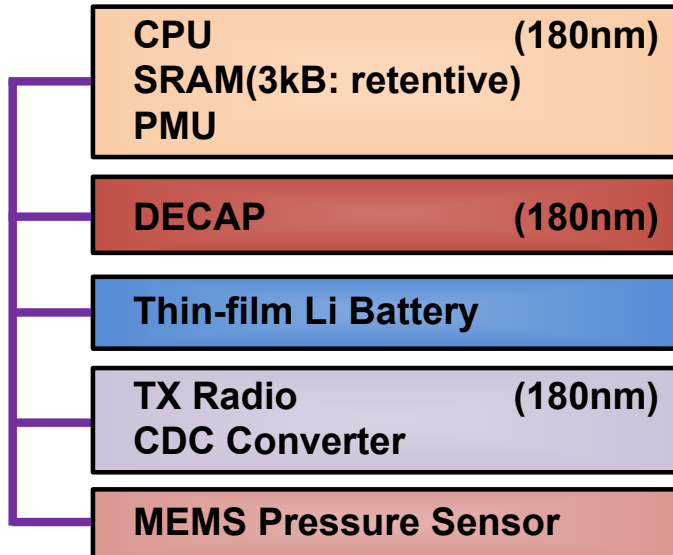
1st System

- Motion detection surveillance sensor
 - Application specific: Motion detector layer
 - Motion detection in standby mode (200nW)
 - Data transmission in active mode (40μW)



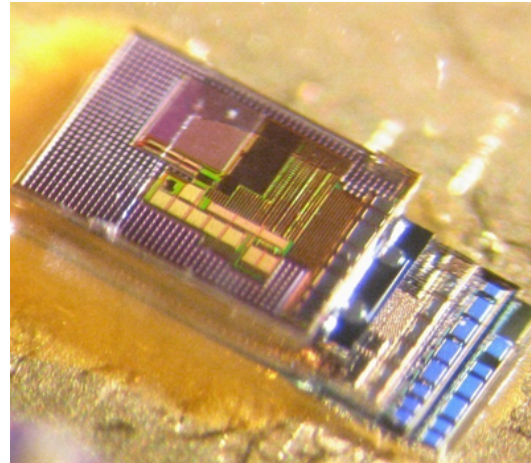
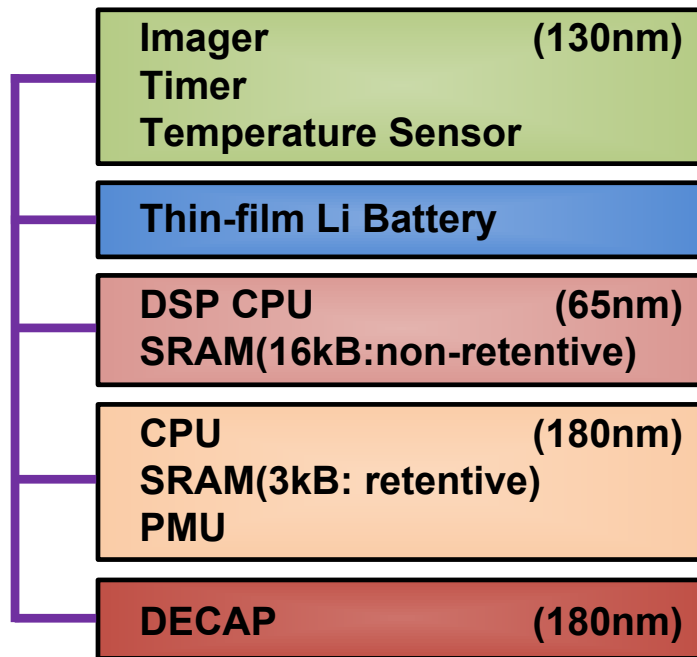
2nd System

- Implantable medical sensor (tumor pressure monitoring)
 - Application specific: MEMS pressure sensor
CDC conversion



3rd System

- Imager and Temperature monitoring
 - Application specific: Imager
Temperature sensor



Thank You